	PCN Number: 20160628			009		PCN Date:		7/1/2016			
Title: Datasheet for LMV7219								., _,			
Customer Contact: PCN Manager			1		ept: Qua		lity Services				
Cha	nge Type:		·					•			
	Assembly Site		Desi	gn		Wafer	Bum	p Site			
	Assembly Process	S		Sheet			r Bump Material				
	Assembly Materials		Part	number change		Wafer	Wafer Bump Process				
	Mechanical Specification		Test	Site		Wafer	er Fab Site				
	Packing/Shipping/Labeling		Test	Process		Wafer	Wafer Fab Materials				
						Wafer Fab Process					
Notification Details											
	cription of Chan										
Texa	as Instruments Inc	corporated is a	announci	ng an information onl	y not	ificatio	n.				
The	following change Texas Instruments	history provid	les furthe					LMV7219			
_				SN	NOS458I -	-APRIL 200	0-REVIS	ED JUNE 2016			
Cha	anges from Revision H	(April 2016) to Rev	vision I					Page			
	Added Supports 105°C F	CB Temperature to	Added Supports 105°C PCB Temperature to Features List								
Changed Operating Temperature to Ambient Temperature											
•	Changed Operating Tem	perature to Ambien	nt Temperatu	re				4			
				re							
•	Added Junction Tempera Added PCB Temperature	ature of 125 °C e of 105 °C						4 4			
•	Added Junction Tempera Added PCB Temperature	ature of 125 °C e of 105 °C						4 4			
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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